



General Features

- $R_{DS(ON)}$ <21mΩ @ VGS = -4.5V $R_{DS(ON)}$ <28mΩ @ VGS = -2.5V
- High Power and Current Handing Capability
- Lead Free Product is Acquired
- Surface Mount Package

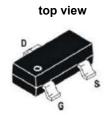
Product Summary



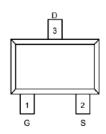
VDS	-20	V
RDS(on),max.@ VGS=4.5 V	21	mΩ
ID	-9	Α

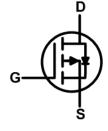
Applications

- PWM Applications
- Load Switch
- ●Power Management









P-channel

Absolute Maximum Ratings (T_C=25℃ unless otherwise specified)

Symbol	Parameter		Max.	Units
V _{DSS}	Drain-Source Voltage		-20	V
V _{GSS}	Gate-Source Voltage		±12	V
ı	Continuous Drain Comment	T _C = 25°C	-9	А
I _D	Continuous Drain Current	T _C = 100°C	-5	
I _{DM}	Pulsed Drain Current note1		-15	Α
PD	Power Dissipation	T _C = 25°C	1.8	W
RθJA	Thermal Resistance, Junction to Ambient		125	°C/W
TJ, Tstg	Operating and Storage Temperature Range		-55 to +150	$^{\circ}$ C

Electrical Characteristics (Tc=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Characteristic						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V,I _D = -250μA	-20	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -20V, V _{GS} = 0V,	-	-	-1	μΑ
Igss	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±12V	-	-	±100	nA
On Charac	teristics					
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250μA	-0.4	-0.7	-1.0	V
Б	Static Drain-Source on-Resistance	V _{GS} =-4.5V, I _D =-4.A	-	16	21	0
R _{DS(on)}	note2	V _{GS} =-2.5V, I _D =-3.A	-	20	28	mΩ
g FS	Forward Transconductance	V _{DS} =-5V, I _D = -6.7A	20	-	-	S
Dynamic (Characteristics					
Ciss	Input Capacitance	10)/11/	-	1200	-	pF
Coss	Output Capacitance	$V_{DS} = -10V, V_{GS} = 0V,$	-	230	-	pF
Crss	Reverse Transfer Capacitance	f = 1.0MHz	-	90	-	pF
Qg	Total Gate Charge	101/1	-	15	48	nC
Qgs	Gate-Source Charge	$V_{DS} = -16V, I_D = -9A,$ $V_{GS} = -4.5V$	-	4	-	nC
Qgd	Gate-Drain("Miller") Charge	V _{GS} = -4.5V	-	6	-	nC
Switching	Switching Characteristics					
t _{d(on)}	Turn-on Delay Time		-	11	-	ns
tr	Turn-on Rise Time	$V_{DD} = -10V$, $I_{D} = -1A$,	-	18	-	ns
t _{d(off)}	Turn-off Delay Time	R_{GEN} =10 Ω , V_{GS} =-4.5 V	-	30	-	ns
t f	Turn-off Fall Time		-	10	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
ls	Maximum Continuous Drain to Source Diode Forward Current		-	-	-1	Α
Ism	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-10	А
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = -8A	-	-	-1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

^{2.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤2%



■ Typical Performance Characteristics

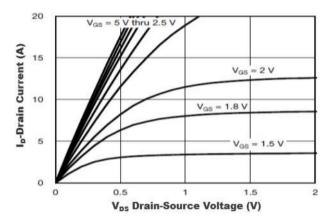


Figure 1. Output Characteristics

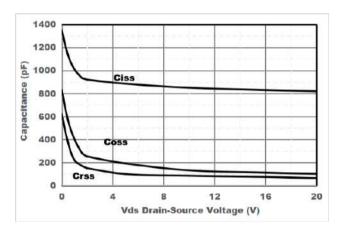


Figure 3. Capacitance Characteristics

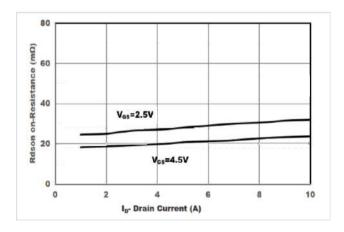


Figure 5. Drain-Source on Resistance

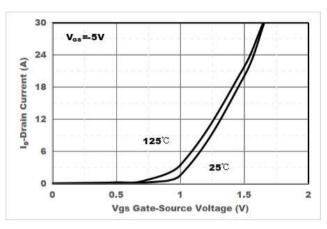


Figure 2. Transfer Characteristics

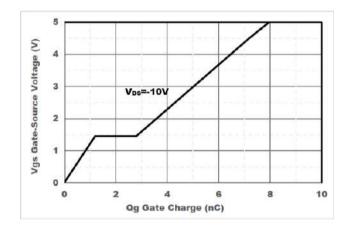


Figure 4. Gate Charge

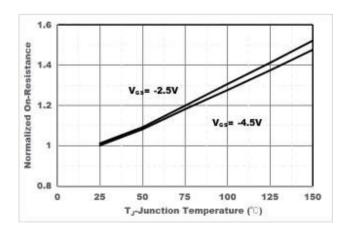


Figure 6. Drain-Source on Resistance



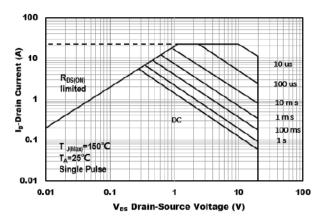


Figure7. Safe Operation Area

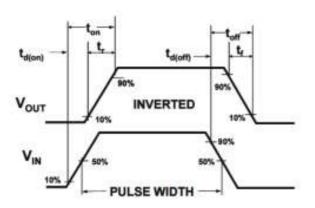


Figure8. Switching wave



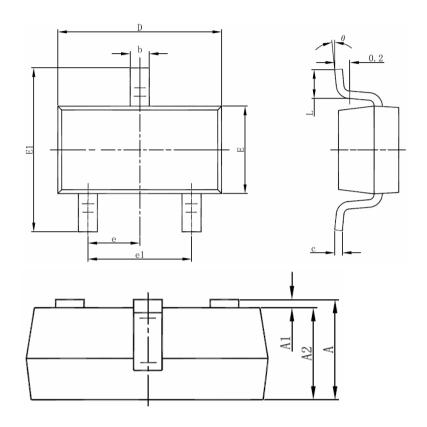
Ordering and Marking Information

Ordering Device No	Marking	Package	Packing	Quantity
ASDM20P09ZB-R	20P09	SOT23-3	Tape&Reel	3000/Reel

PACKAGE	MARKING
SOT23-3	20P09 ☐ ——▶ Lot Number



SOT-23-3L PACKAGE INFORMATION



Combo a l	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E	1.500	1.700	0.059	0.067	
E1	2.650	2.950	0.104	0.116	
е	0.950(BSC)		0.037(BSC)		
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	



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ASDM20P09ZB

-20V P-Channel MOSFET

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